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## 03/30/2011

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#### RECORDATION FORM COVER SHEET To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies) Sung-soo PARK Name: Samsung Electronics Co., Ltd. Moon-sang LEE Additional name(s) of conveying party(ies) attached? Street Address. 416, Maetan-dong, Yeongtong-gu JYES ⊠NO 3. Nature of conveyance: City: Suwon-si State: Gyeonggi-do Assignment ☐ Merger ☐ Security Agreement ☐ Change of Name Country: Republic of Korea Other: Execution Date: March 24, 2011; March 24, 2011 Additional name(s) & address(es) attached? YES NO 4. Application number(s) or patent number(s). If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No(s). B. Patent No.(s). 12/929,856 5 Name and address of party to whom correspondence 6. Total No. of applications/patents involved. One (1) concerning document should be mailed. 7. Total fee (37 C.F.R. § 3 41) Name: HARNESS, DICKEY & PIERCE, P.L.C. \$40.00 □ Enclosed Street Address: P.O. BOX 8910 Authorized to be charged to deposit account, City. **RESTON** State: VA ZIP: 20195 if no fee attached Country: USA 8. Deposit account number: 08-0750 (Attach triplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document John A. Castellano, Reg. No. 35,094 Name of Person Signing/Reg No March 28, 2011 Signature Total number of pages including cover sheet, attachments, and document: <del>03/30/2011 AMULLINS 000000</del>06 1c329856

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#### **ASSIGNMENT**

WHEREAS, the undersigned, hereinafter referred to collectively as Assignor, has invented.

# METHODS OF GROWING NITRIDE SEMICONDUCTORS AND METHODS OF MANUFACTURING NITRIDE SEMICONDUCTOR SUBSTRATES

WHEREAS, Samsung Electronics Co., Ltd., 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, hereinafter referred to as Assignee, is desirous of acquiring all right, title, and interest therein

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy whereof is hereby acknowledged, Assignor hereby confirms any prior assignment to Assignee, and to the extent that Assignor has not already done so, agrees to assign, and hereby does, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment, and

Assignor hereby requests the United States Patent and Trademark Office to issue the Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as aforesaid, to issue the Letters Patent, Utility Model Registration or other similar right to Assignee.

The undersigned hereby grant(s) the law firm of Harness, Dickey & Pierce, PLC the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

PATENT REEL: 026087 FRAME: 0649

### **ASSIGNMENT**

Sung-soo PARK

March 24. 2011

Dated

Moon-sang LEE

March 24, 2011

Dated

**RECORDED: 03/28/2011** 

PATENT REEL: 026087 FRAME: 0650